Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	53447	(conduct$3 wir$3) same mask same (expos$3 remov$3 etch$3 pattern$3)	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/29 18:56
L3	10735	L2 and ((IC die chip) same (connect$3 fitt$3))	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/29 18:56
L4	7294	L3 and (electrical$3 near5 connect$3)	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/29 18:57
L5	6425	L4 and (insulat$3 dielectric)	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/29 17:49
L6	2859	L5 and resin	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/29 18:57
L11	28146	(conduct$3 wir$3) and mask and (expos$3 remov$3 etch$3 pattern$3)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/29 18:56
L12	817	L11 and ((IC die chip) and (connect$3 fitt$3))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/29 18:56
L13	277	L12 and (electrical$3 and connect$3)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/29 18:57
L14	137	L13 and (insulat$3 resin)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/29 18:57